

### 描述 / Descriptions

表面贴装肖特基整流二极管，反向电压：20V~200V，正向电流：2.0A，SMA封装。

Surface Mount Schottky Barrier Rectifiers, Reverse Voltage : 20 to 200V, Forward Current: 2.0A, SMA package.

### 特征 / Features

玻璃钝化芯片，无铅符合欧盟 RoHS 指令 2011/65/EU，适用表面贴装。无卤产品。

Glass Passivated Chip Junction, Lead free in comply with EU RoHS 2011/65/EU directives, For surface mounted applications. HF product.

### 用途 / Applications

一般用途。

General purpose.

### 内部等效电路 / Equivalent Circuit

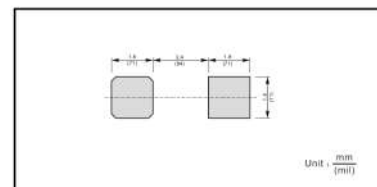


### 引脚排列 / Pinning



PIN	DESCRIPTION
1	Cathode
2	Anode

The recommended mounting pad size



### 印章代码 / Marking

见印章说明。See Marking Instructions.

**极限参数 / Absolute Maximum Ratings(Ta=25°C)**

参数 Parameter	符号 Symbol	数值 Rating								单位 Unit
		SS22	SS24	SS26	SS28	SS210	SS212	SS215	SS220	
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	20	40	60	80	100	120	150	200	V
Maximum RMS voltage	$V_{RMS}$	14	28	42	56	70	84	105	140	V
Maximum DC Blocking Voltage	$V_{DC}$	20	40	60	80	100	120	150	200	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	2.0								A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	$I_{FSM}$	50								A
Typical Junction Capacitance at $V_R=4V$ $f=1MHz$	$C_j$	220		80						pF
Typical Thermal Resistance <sup>1)</sup>	$R_{\theta JA}$	80								°C/W
Operating and Storage Temperature Range	$T_j, T_{stg}$	-55~+150								°C

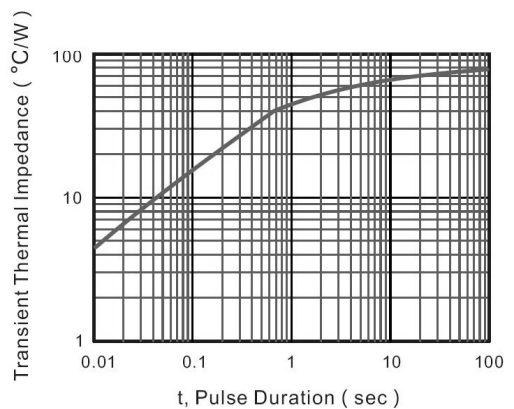
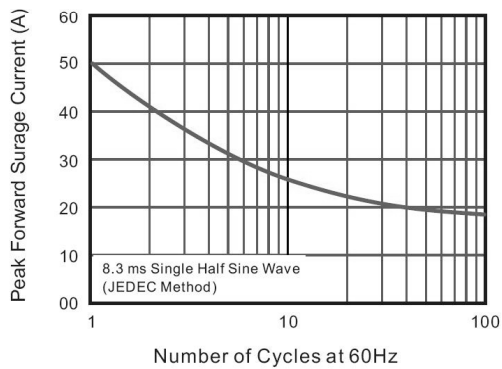
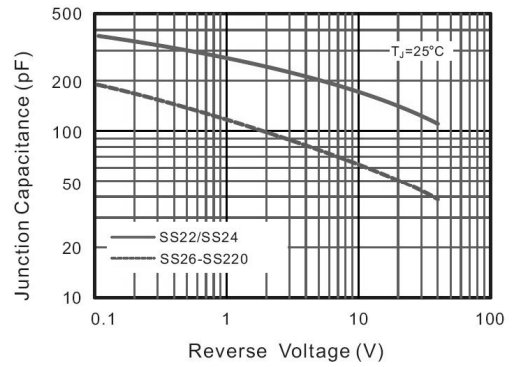
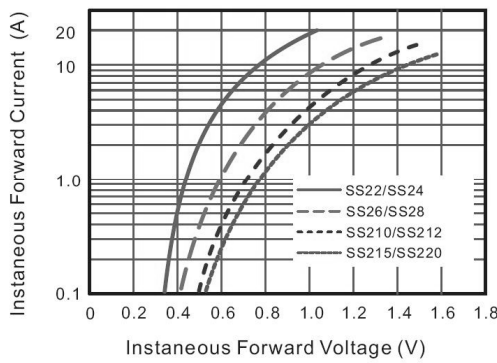
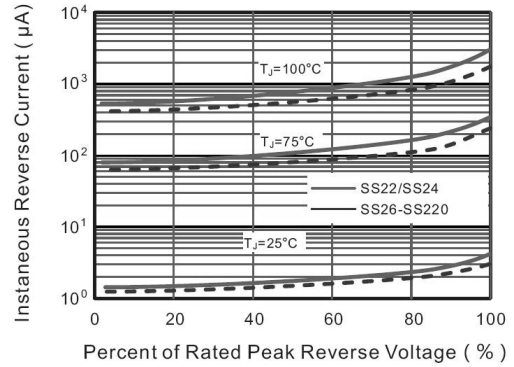
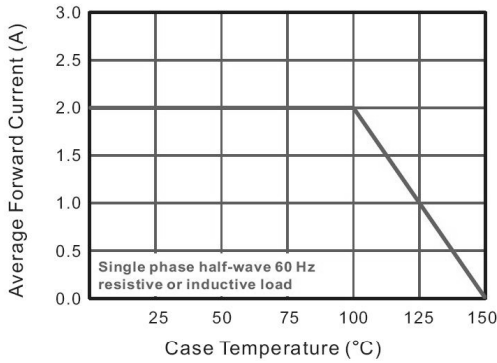
Note:

1) P.C.B. mounted with 2.0 X 2.0" (5 X5 cm) copper pad areas.

**电性能参数 / Electrical Characteristics(Ta=25°C)**

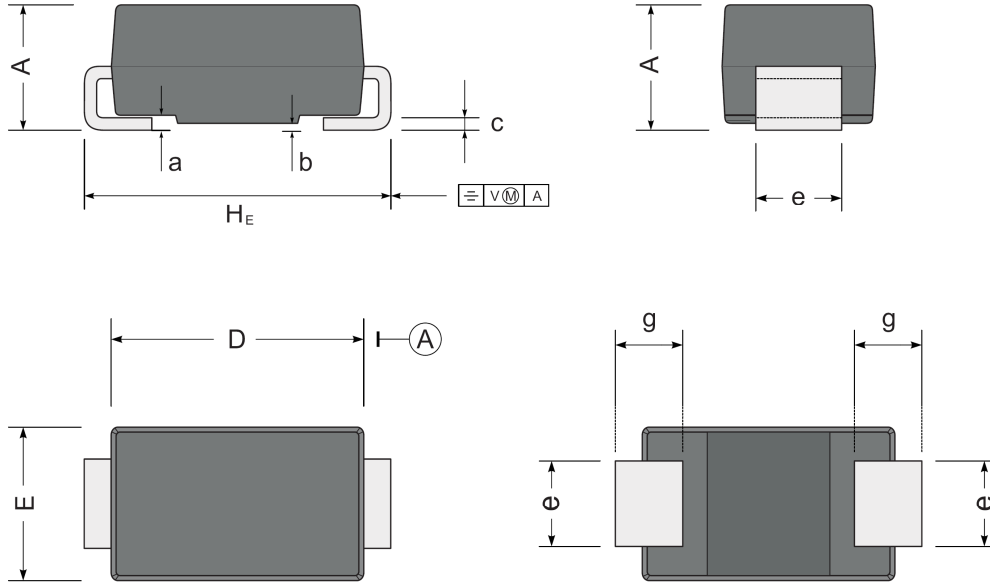
参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating								单位 Unit
			SS22	SS24	SS26	SS28	SS210	SS212	SS215	SS220	
Maximum Instantaneous Forward Voltage	$V_F$	$I_F=2.0A$	0.55		0.70	0.85			0.95	V	
Maximum DC Reverse Current at Rated DC Blocking Voltage	$I_R$	$T_a=25^\circ C$	0.5			0.3				mA	
		$T_a=100^\circ C$	5.0			3.0				mA	

电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions

SMA

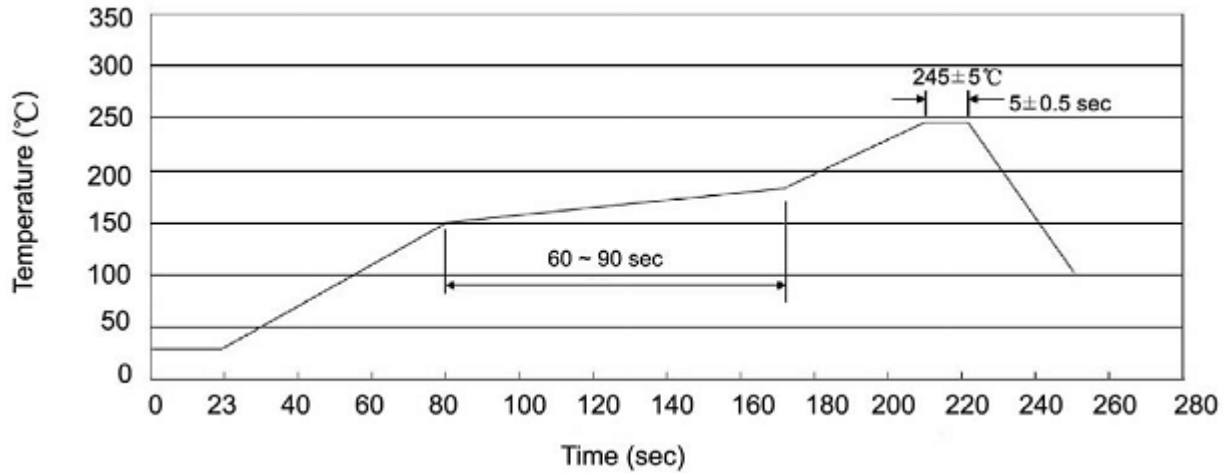


UNIT		A	D	E	H <sub>E</sub>	c	e	g	b	a
mm	max	2.2	4.5	2.7	5.2	0.31	1.6	1.5	0.2	0.3
	min	1.9	4.0	2.3	4.7	0.15	1.3	0.9	0.05	
mil	max	87	181	106	205	12	63	59	7.9	12
	min	75	157	91	185	6	51	35	2	

印章说明 / Marking Instructions

Type number	Marking code
SS22	SS22
SS24	SS24
SS26	SS26
SS28	SS28
SS210	SS210
SS212	SS212
SS215	SS215
SS220	SS220

**回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)**



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

**耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions**

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

**包装规格 / Packaging SPEC.**

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
SMA	5000	2	10000	7	70000	13" ×12	336X336X40	380X335X366

**使用说明 / Notices**